TEXAS INSTRUMENTS

uA741

SLOS094F – NOVEMBER 1970 – REVISED MAY 2017

µA741 General-Purpose Operational Amplifiers

1 Features

- Short-Circuit Protection
- Offset-Voltage Null Capability
- Large Common-Mode and Differential Voltage Ranges
- No Frequency Compensation Required
- No Latch-Up

2 Applications

- DVD Recorders and Players
- Pro Audio Mixers

3 Description

The µA741 device is a general-purpose operational amplifier featuring offset-voltage null capability.

The high common-mode input voltage range and the absence of latch-up make the amplifier ideal for voltage-follower applications. The device is short-circuit protected and the internal frequency compensation ensures stability without external components. A low-value potentiometer may be connected between the offset null inputs to null out the offset voltage as shown in Figure 12.

The µA741C device is characterized for operation from 0°C to 70°C.

Device Information[(1)]

PART NUMBER	PACKAGE	BODY SIZE (NOM)
µA741CD	SOIC (8)	4.90 mm × 3.91 mm
µA741CP	PDIP (8)	9.81 mm × 6.35 mm
µA741CPS	SO (8)	6.20 mm × 5.30 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.
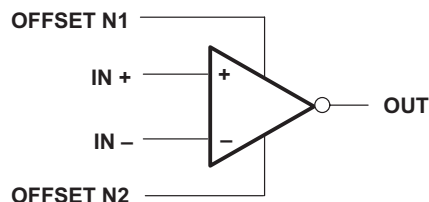
Simplified Schematic

Table of Contents

4 Revision History

Changes from Revision E (January 2015) to Revision F **Page**

Changes from Revision D (February 2014) to Revision E **Page**

5 Pin Configurations and Functions

uA741C D, P, or PS Package
8-Pin SOIC, PDIP, SO
Top View

OFFSET N1	1		8	NC
IN–	2		7	VCC+
IN+	3		6	OUT
VCC–	4		5	OFFSET N2

Not to scale
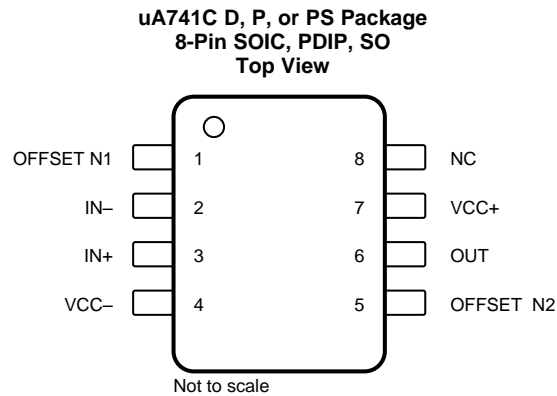
(1) NC- no internal connection

Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
IN+	3	I	Noninverting input
IN–	2	I	Inverting input
NC	8	—	No internal connection
OFFSET N1	1	I	External input offset voltage adjustment
OFFSET N2	5	I	External input offset voltage adjustment
OUT	6	O	Output
VCC+	7	—	Positive supply
VCC–	4	—	Negative supply

Product Folder Links: *uA741*

6 Specifications

6.1 Absolute Maximum Ratings

over virtual junction temperature range (unless otherwise noted)[1]

				MIN	MAX	UNIT
V_{CC}	Supply voltage[2]	μA741C		−18	18	°C
V_{ID}	Differential input voltage[3]	μA741C		−15	15	V
V_I	Input voltage, any input[2][4]	μA741C		−15	15	V
	Voltage between offset null (either OFFSET N1 or OFFSET N2) and V_{CC-}	μA741C		−15	15	V
	Duration of output short circuit[5]				Unlimited	
	Continuous total power dissipation				See *Thermal Information*	
	Case temperature for 60 seconds		μA741C	N/A	N/A	°C
	Lead temperature 1.6 mm (1/16 inch) from case for 60 seconds		μA741C	N/A	N/A	°C
	Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds	D, P, or PS package	μA741C		260	°C
	Operating junction temperature, T_J				150	°C
	Storage temperature range, T_{stg}		μA741C	−65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-}.
(3) Differential voltages are at IN+ with respect to IN –.
(4) The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
(5) The output may be shorted to ground or either power supply.

6.2 Recommended Operating Conditions

			MIN	MAX	UNIT
V_{CC+}	Supply voltage		5	15	V
V_{CC-}			−5	−15	
T_A	Operating free-air temperature	μA741C	0	70	°C

6.3 Thermal Information

THERMAL METRIC[1]		μA741			UNIT
		D (SOIC)	P (PDIP)	PS (SO)	
		8 PINS	8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	129.2	87.4	119.7	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	73.6	89.3	66	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	72.4	64.4	70	°C/W
ψ_{JT}	Junction-to-top characterization parameter	25.9	49.8	27.2	°C/W
ψ_{JB}	Junction-to-board characterization parameter	71.7	64.1	69	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

6.4 Electrical Characteristics μA741C

at specified virtual junction temperature, $V_{CC\pm} = \pm15$ V (unless otherwise noted)

	PARAMETER	TEST CONDITIONS[1]		MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	$V_O = 0$	25°C		1	6	mV
			Full range			7.5	
$\Delta V_{IO(adj)}$	Offset voltage adjust range	$V_O = 0$	25°C		±15		mV
I_{IO}	Input offset current	$V_O = 0$	25°C		20	200	nA
			Full range			300	
I_{IB}	Input bias current	$V_O = 0$	25°C		80	500	nA
			Full range			800	
V_{ICR}	Common-mode input voltage range	25°C		±12	±13		V
		Full range		±12			
V_{OM}	Maximum peak output voltage swing	$R_L = 10$ kΩ	25°C	±12	±14		V
		$R_L \geq 10$ kΩ	Full range	±12			
		$R_L = 2$ kΩ	25°C	±10			
		$R_L \geq 2$ kΩ	Full range	±10			
A_{VD}	Large-signal differential voltage amplification	$R_L \geq 2$ kΩ	25°C	20	200		V/mV
		$V_O = \pm10$ V	Full range	15			
r_i	Input resistance	25°C		0.3	2		MΩ
r_o	Output resistance	$V_O = 0$; see[2]	25°C		75		Ω
C_i	Input capacitance	25°C			1.4		pF
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICRmin}$	25°C	70	90		dB
			Full range	70			
k_{SVS}	Supply voltage sensitivity ($\Delta V_{IO}/\Delta V_{CC}$)	$V_{CC} = \pm9$ V to ±15 V	25°C		30	150	μV/V
			Full range			150	
I_{OS}	Short-circuit output current	25°C			±25	±40	mA
I_{CC}	Supply current	$V_O = 0$; no load	25°C		1.7	2.8	mA
			Full range			3.3	
P_D	Total power dissipation	$V_O = 0$; no load	25°C		50	85	mW
			Full range			100	

(1) All characteristics are measured under open-loop conditions with zero common-mode input voltage unless otherwise specified.
Full range for the μA741C is 0°C to 70°C.
(2) This typical value applies only at frequencies above a few hundred hertz because of the effects of drift and thermal feedback.

Product Folder Links: *uA741*

6.5 Electrical Characteristics: μA741Y

at specified virtual junction temperature, $V_{CC\pm}$ = ±15 V, T_A = 25°C (unless otherwise noted)[1]

	PARAMETER	TEST CONDITIONS [2]	MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	V_O = 0		1	5	mV
$\Delta V_{IO(adj)}$	Offset voltage adjust range	V_O = 0		±15		mV
I_{IO}	Input offset current	V_O = 0		20	200	nA
I_{IB}	Input bias current	V_O = 0		80	500	nA
V_{ICR}	Common-mode input voltage range		±12	±13		V
V_{OM}	Maximum peak output voltage swing	R_L = 10 kΩ	±12	±14		V
		R_L = 2 kΩ	±10	±13		
A_{VD}	Large-signal differential voltage amplification	R_L ≥ 2 kΩ	20	200		V/mV
r_i	Input resistance		0.3	2		MΩ
r_o	Output resistance	V_O = 0; see[1]		75		Ω
C_i	Input capacitance			1.4		pF
CMRR	Common-mode rejection ratio	V_{IC} = V_{ICRmin}	70	90		dB
k_{SVS}	Supply voltage sensitivity ($\Delta V_{IO}/\Delta V_{CC}$)	V_{CC} = ±9 V to ±15 V		30	150	μV/V
I_{OS}	Short-circuit output current			±25	±40	mA
I_{CC}	Supply current	V_O = 0; no load		1.7	2.8	mA
P_D	Total power dissipation	V_O = 0; no load		50	85	mW

(1) This typical value applies only at frequencies above a few hundred hertz because of the effects of drift and thermal feedback.
(2) All characteristics are measured under open-loop conditions with zero common-mode voltage unless otherwise specified.

6.6 Switching Characteristics μA741C

over operating free-air temperature range, $V_{CC\pm}$ = ±15 V, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_r	Rise time	V_I = 20 mV, R_L = 2 kΩ C_L = 100 pF; see Figure 1		0.3		μs
	Overshoot factor			5%		
SR	Slew rate at unity gain	V_I = 10 V, R_L = 2 kΩ C_L = 100 pF; see Figure 1		0.5		V/μs

6.7 Switching Characteristics μA741Y

over operating free-air temperature range, $V_{CC\pm}$ = ±15 V, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_r	Rise time	V_I = 20 mV, R_L = 2 kΩ C_L = 100 pF; see Figure 1		0.3		μs
	Overshoot factor			5%		
SR	Slew rate at unity gain	V_I = 10 V, R_L = 2 kΩ C_L = 100 pF; see Figure 1		0.5		V/μs

TEXAS
INSTRUMENTS

6.8 Typical Characteristics

Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.
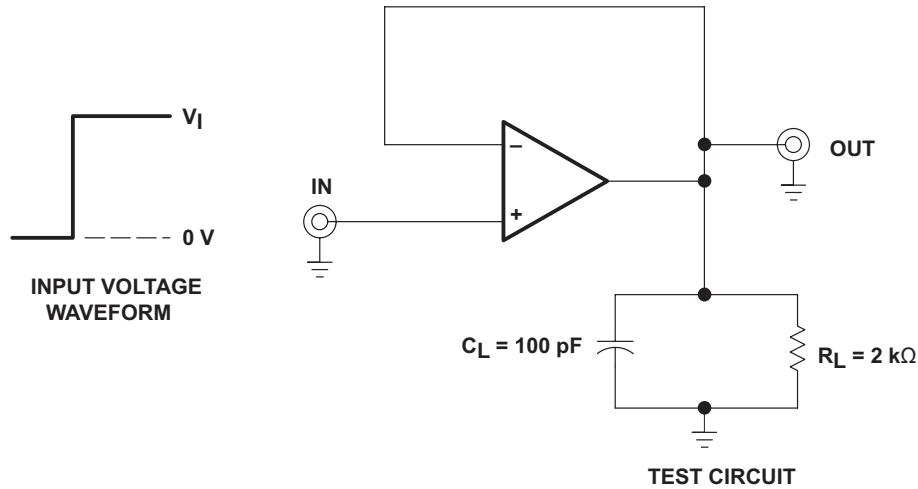
Figure 1. Rise Time, Overshoot, and Slew Rate
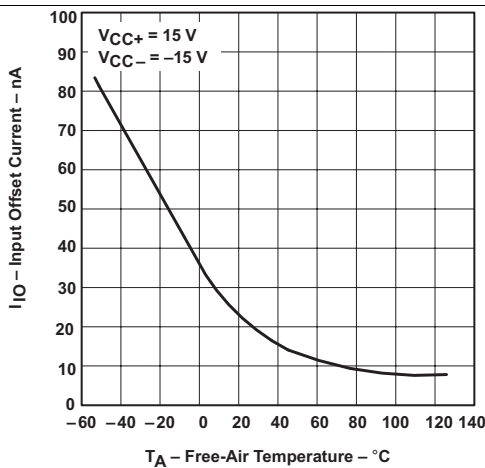
Figure 2. Input Offset Current vs Free-Air Temperature
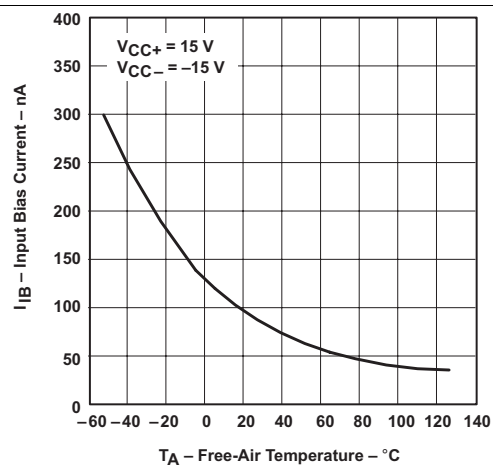
Figure 3. Input Bias Current vs Free-Air Temperature
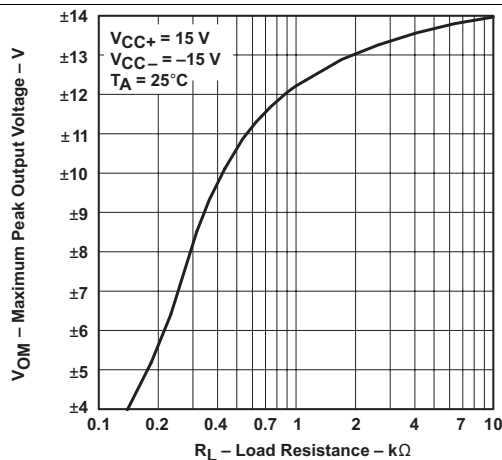
Figure 4. Maximum Output Voltage vs Load Resistance
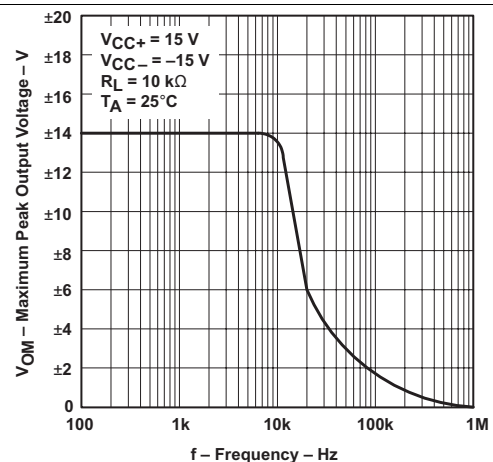
Figure 5. Maximum Peak Output Voltage vs Frequency

Product Folder Links: *uA741*

Typical Characteristics (continued)

Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.
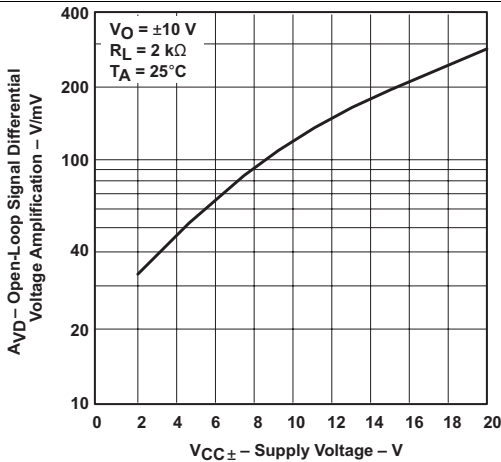
Figure 6. Open-Loop Signal Differential Voltage Amplification vs Supply Voltage
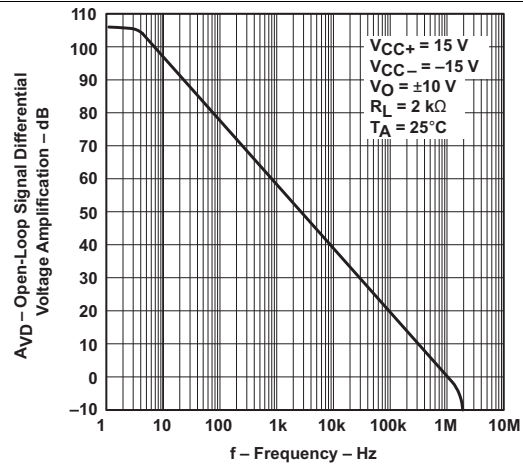
Figure 7. Open-Loop Large-Signal Differential Voltage Amplification vs Frequency
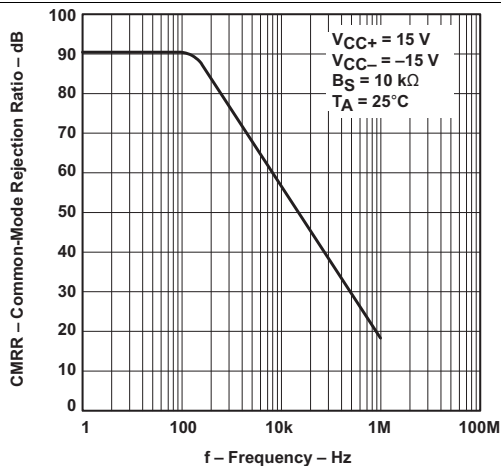
Figure 8. Common-Mode Rejection Ratio vs Frequency
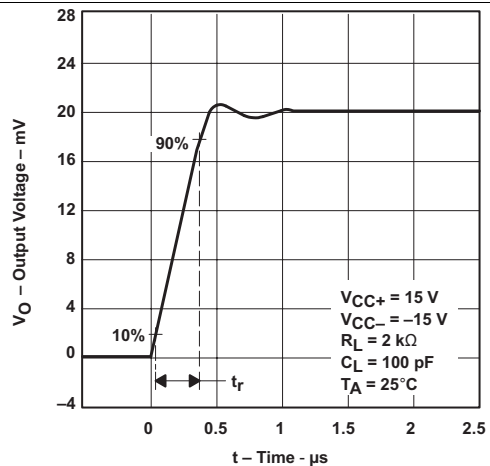
Figure 9. Output Voltage vs Elapsed Time
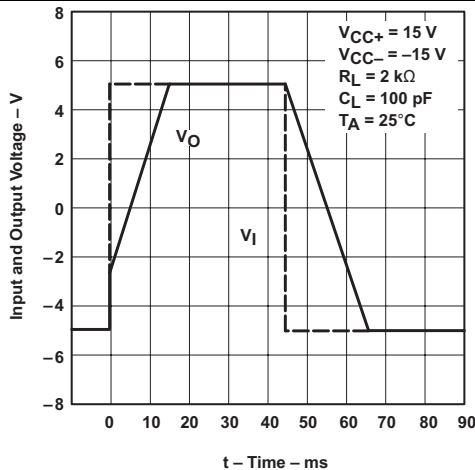
Figure 10. Voltage-Follower Large-Signal Pulse Response

Product Folder Links: *uA741*

7 Detailed Description

7.1 Overview

The μA741 has been a popular operational amplifier for over four decades. Typical open loop gain is 106 dB while driving a 2000-Ω load. Short circuit tolerance, offset voltage trimming, and unity-gain stability makes the μA741 useful for many applications.

7.2 Functional Block Diagram
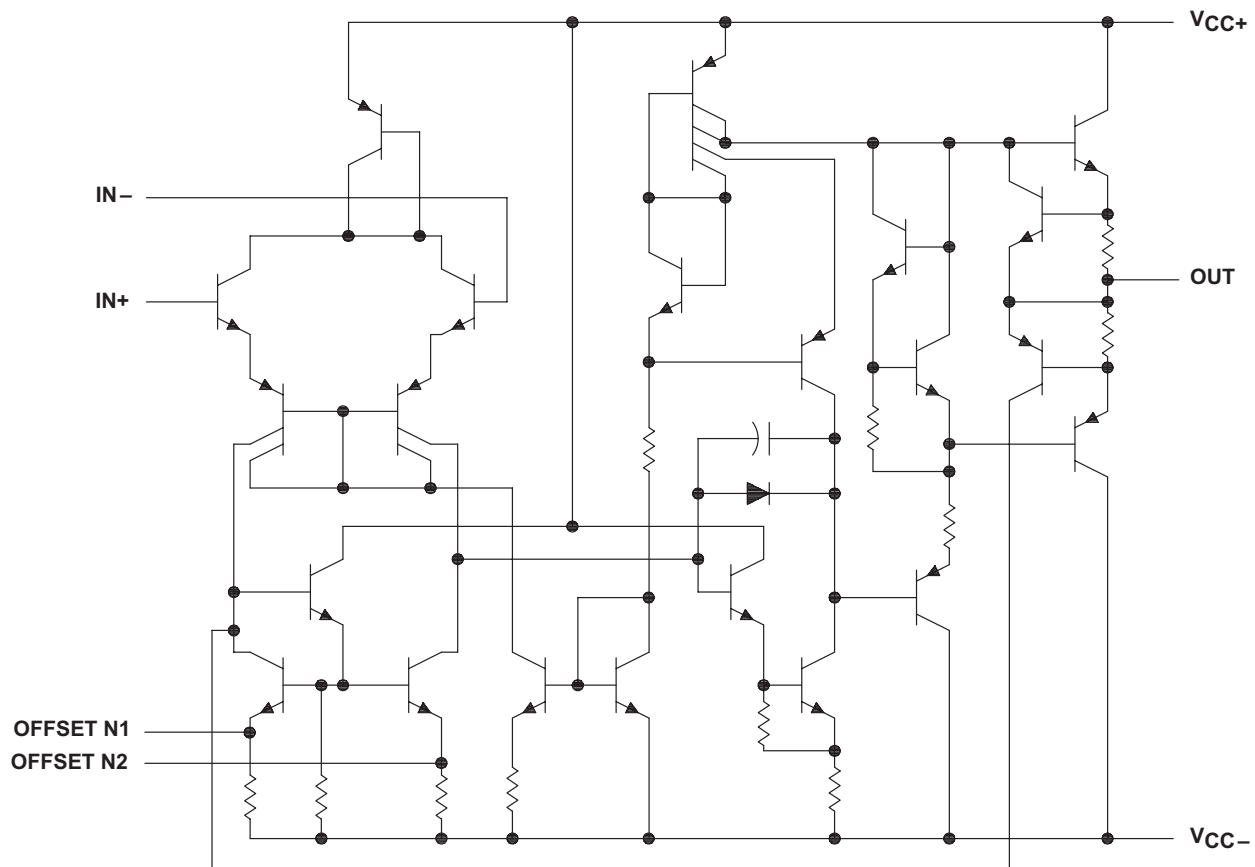
Component Count	
Transistors	22
Resistors	11
Diode	1
Capacitor	1

Copyright © 2017, Texas Instruments Incorporated

7.3 Feature Description

7.3.1 Offset-Voltage Null Capability

The input offset voltage of operational amplifiers (op amps) arises from unavoidable mismatches in the differential input stage of the op-amp circuit caused by mismatched transistor pairs, collector currents, current-gain betas (β), collector or emitter resistors and so forth. The input offset pins allow the designer to adjust for mismatches caused by external circuitry. See *Application and Implementation* for more details on design techniques.

Feature Description (continued)

7.3.2 Slew Rate

The slew rate is the rate at which an operational amplifier can change an output when there is a change on the input. The µA741 device has a 0.5-V/µs slew rate. Parameters that vary significantly with operating voltages or temperature are shown in *Typical Characteristics*.

7.4 Device Functional Modes

The µA741 device is powered on when the power supply is connected. The device can operate as a single-supply or dual-supply operational amplifier depending on the application.

7.5 µA741Y Chip Information

When properly assembled, this chip displays characteristics similar to the µA741C device. Thermal compression or ultrasonic bonding may be used on the doped-aluminum bonding pads. Chips can be mounted with conductive epoxy or a gold-silicon preform.
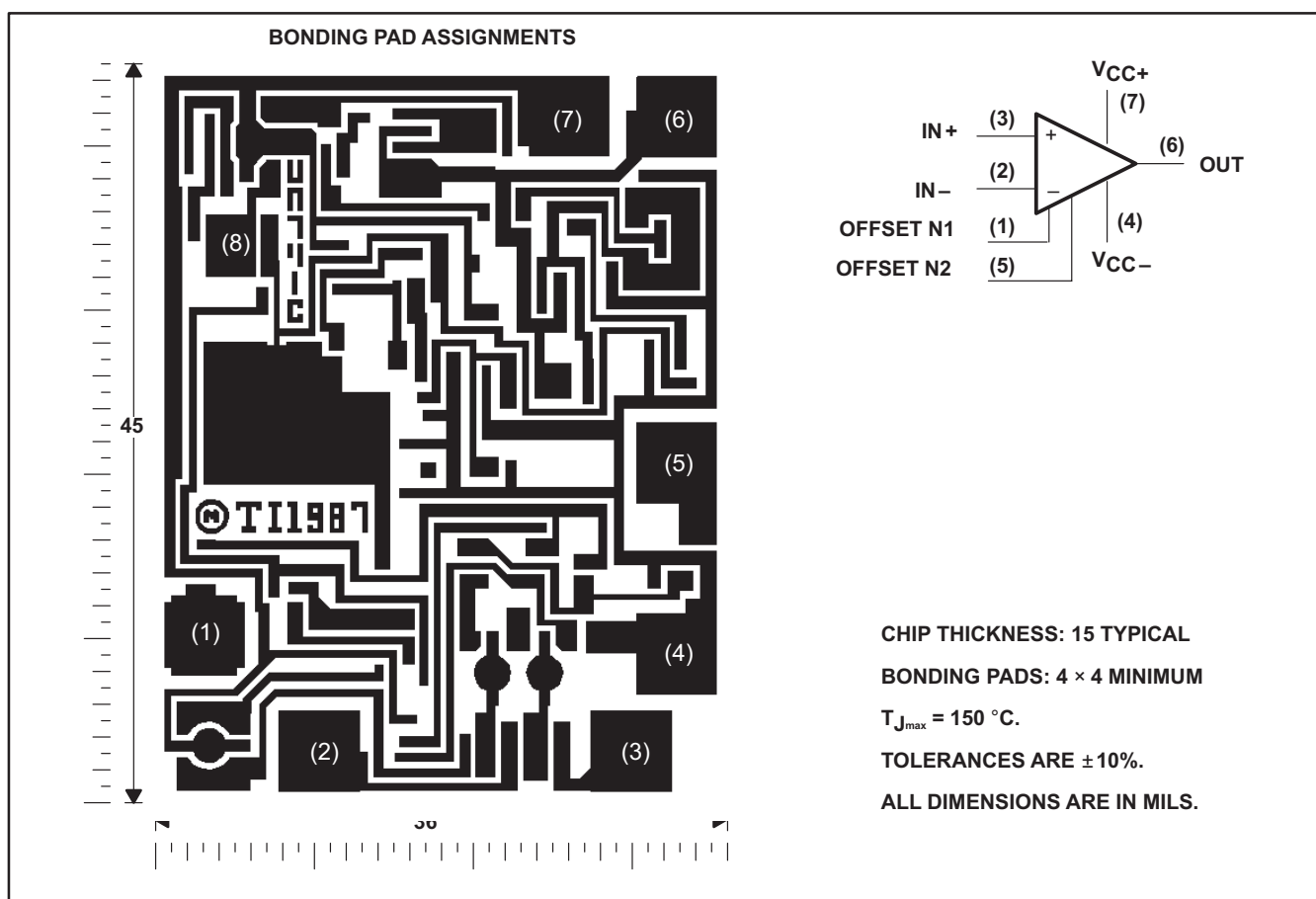
Figure 11. Bonding Pad Assignments

Product Folder Links: *uA741*

8 Application and Implementation

> **NOTE**
>
> Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The input offset voltage of operational amplifiers (op amps) arises from unavoidable mismatches in the differential input stage of the op-amp circuit caused by mismatched transistor pairs, collector currents, current-gain betas (β), collector or emitter resistors and so forth. The input offset pins allow the designer to adjust for mismatches resulting from external circuitry. These input mismatches can be adjusted by placing resistors or a potentiometer between the inputs as shown in Figure 12. A potentiometer can fine-tune the circuit during testing or for applications which require precision offset control. For more information about designing using the input-offset pins, see *Nulling Input Offset Voltage of Operational Amplifiers*.
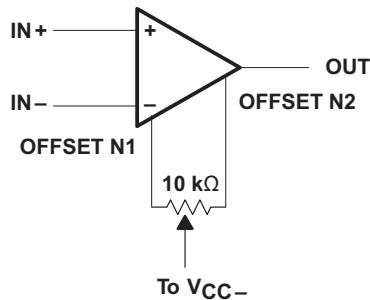
Figure 12. Input Offset Voltage Null Circuit

8.2 Typical Application

The voltage follower configuration of the operational amplifier is used for applications where a weak signal drives a relatively high current load. This circuit is also called a buffer amplifier or unity-gain amplifier. The inputs of an operational amplifier have a very high resistance which puts a negligible current load on the voltage source. The output resistance of the operational amplifier is almost negligible, so the resistance can provide as much current as necessary to the output load.
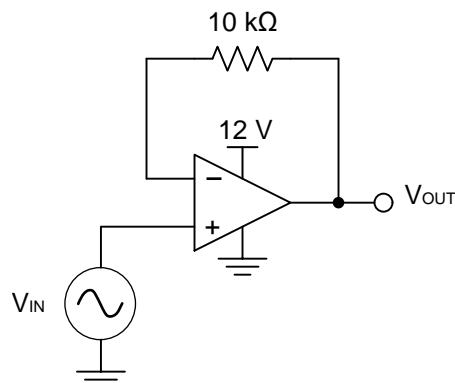
Figure 13. Voltage Follower Schematic

Product Folder Links: *uA741*

Typical Application (continued)

8.2.1 Design Requirements

- Output range from 2 V to 11.5 V
- Input range from 2 V to 11.5 V
- Resistive feedback to negative input

8.2.2 Detailed Design Procedure

8.2.2.1 Output Voltage Swing

The output voltage of an operational amplifier is limited by the internal circuitry to some level below the supply rails. For this amplifier, the output voltage swing is within ±12 V, which accommodates the input and output voltage requirements.

8.2.2.2 Supply and Input Voltage

For correct operation of the amplifier, neither input must be higher than the recommended positive supply rail voltage or lower than the recommended negative supply rail voltage. The selected amplifier must be able to operate at the supply voltage that accommodates the inputs. Because the input for this application goes up to 11.5 V, the supply voltage must be 12 V. Using a negative voltage on the lower rail rather than ground allows the amplifier to maintain linearity for inputs below 2 V.

8.2.3 Application Curves for Output Characteristics
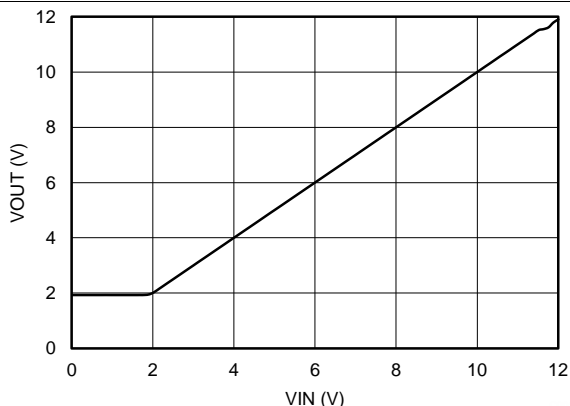
Figure 14. Output Voltage vs Input Voltage
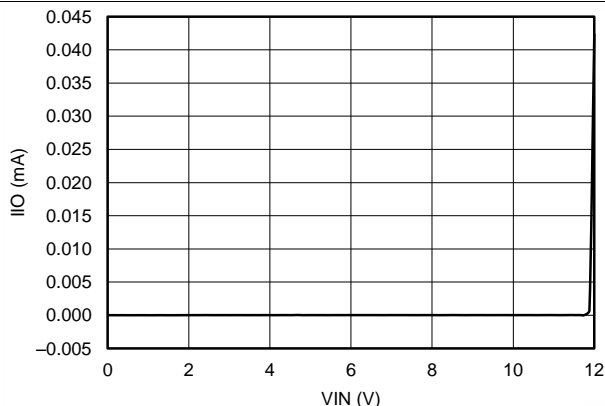
Figure 15. Current Drawn Input of Voltage Follower (I_{IO}) vs Input Voltage
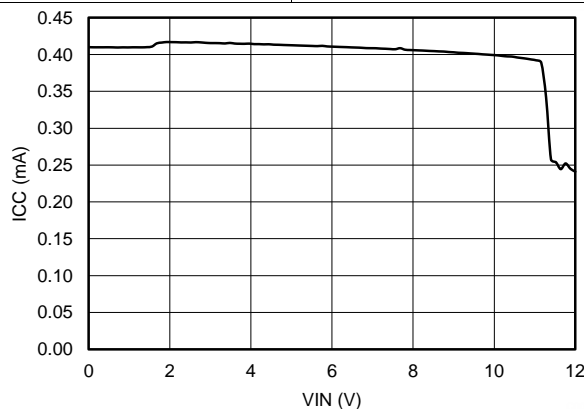
Figure 16. Current Drawn from Supply (I_{CC}) vs Input Voltage

Product Folder Links: *uA741*

9 Power Supply Recommendations

The μA741 device is specified for operation from ±5 to ±15 V; many specifications apply from 0°C to 70°C. *Typical Characteristics* presents parameters that can exhibit significant variance with regard to operating voltage or temperature.

Place 0.1-μF bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high impedance power supplies. For more detailed information on bypass capacitor placement, see *Layout Guidelines*.

CAUTION

Supply voltages larger than ±18 V can permanently damage the device (see *Absolute Maximum Ratings*).

---

10 Layout

10.1 Layout Guidelines

For best operational performance of the device, use good PCB layout practices, including:

- Noise can propagate into analog circuitry through the power pins of the circuit as a whole and the operational amplifier. Bypass capacitors reduce the coupled noise by providing low impedance power sources local to the analog circuitry.
  - Connect low-ESR, 0.1-μF ceramic bypass capacitors between each supply pin and ground, placed as close as possible to the device. A single bypass capacitor from V+ to ground is applicable for single-supply applications.
- Separate grounding for analog and digital portions of circuitry is one of the simplest and most-effective methods of noise suppression. One or more layers on multilayer PCBs are usually devoted to ground planes. A ground plane helps distribute heat and reduces EMI noise pickup. Make sure to physically separate digital and analog grounds, paying attention to the flow of the ground current. For more detailed information, see *Circuit Board Layout Techniques*.
- To reduce parasitic coupling, run the input traces as far away as possible from the supply or output traces. If it is not possible to keep them separate, it is much better to cross the sensitive trace perpendicular as opposed to in parallel with the noisy trace.
- Place the external components as close as possible to the device. Keeping RF and RG close to the inverting input minimizes parasitic capacitance, as shown in *Layout Example*.
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.
- Consider a driven, low-impedance guard ring around the critical traces. A guard ring can significantly reduce leakage currents from nearby traces that are at different potentials.

10.2 Layout Example
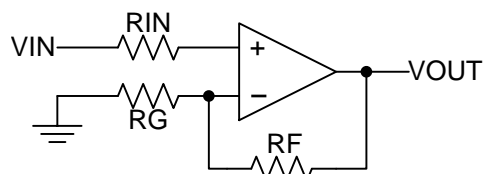
Figure 17. Operational Amplifier Schematic for Noninverting Configuration

Product Folder Links: *uA741*

Layout Example (continued)
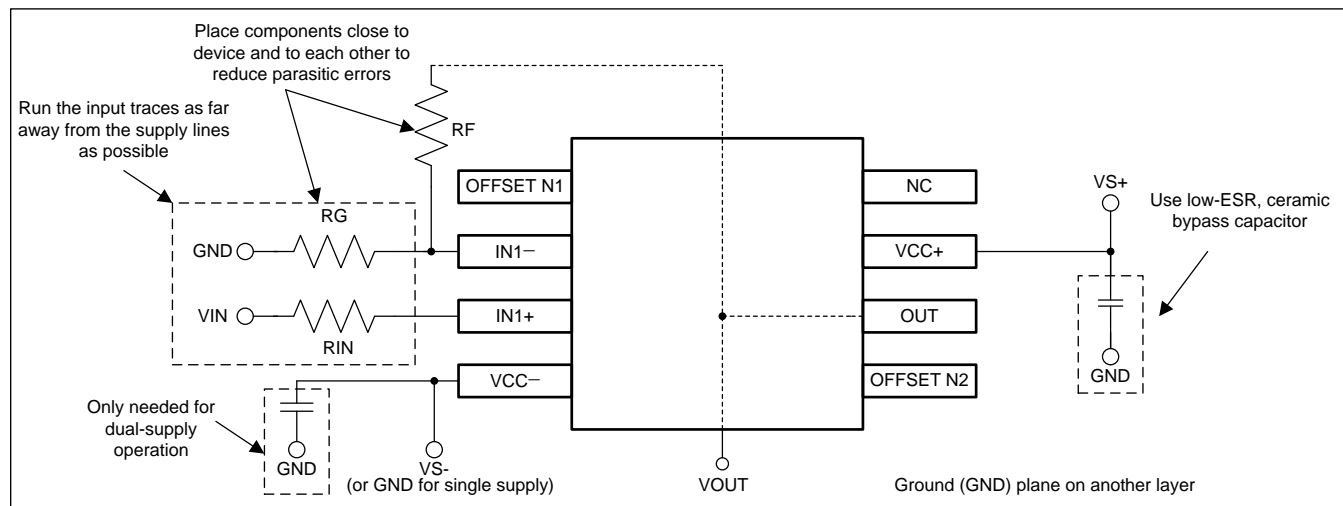
Figure 18. Operational Amplifier Board Layout for Noninverting Configuration

11 Device and Documentation Support

11.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.2 Trademarks

All trademarks are the property of their respective owners.

11.3 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.4 Glossary

SLYZ022 — *TI Glossary*.
    This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UA741CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UA741C	Samples
UA741CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UA741C	Samples
UA741CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UA741C	Samples
UA741CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	UA741C	Samples
UA741CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	UA741CP	Samples
UA741CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	UA741CP	Samples
UA741CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	U741	Samples
UA741CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	U741	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

![Texas Instruments logo]

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

Reel Diameter

Reel Width (W1)

TAPE DIMENSIONS

K0

P1

B0

W

Cavity

A0

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

Sprocket Holes

| Q1 | Q2 |
| Q3 | Q4 |

| Q1 | Q2 |
| Q3 | Q4 |

User Direction of Feed

Pocket Quadrants

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA741CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UA741CPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UA741CDR	SOIC	D	8	2500	340.5	338.1	20.6
UA741CPSR	SO	PS	8	2000	367.0	367.0	38.0

D (R−PDSO−G8) PLASTIC SMALL OUTLINE

0.197 (5,00)
0.189 (4,80)
△C

8   5

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80) △D

Pin 1
Index Area

1   4

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

Gauge Plane

0.004 (0,10)

Seating Plane

0.010 (0,25)

0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−3/M 06/11

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        △C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
            not exceed 0.006 (0,15) each side.
        △D Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
        E. Reference JEDEC MS−012 variation AA.

D (R−PDSO−G8)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

6x1,27

5,40

8x0,55

8x1,50

6x1,27

5,40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,60

1,55

0,07

All Around

Example
Solder Mask Opening
(See Note E)

4211283−2/E 08/12

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Publication IPC−7351 is recommended for alternate designs.
         D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
             contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
         E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

PS (R-PDSO-G8)　　　　　　　　　　　　　　**PLASTIC SMALL-OUTLINE PACKAGE**

4040063/C 03/03

NOTES:　A.　All linear dimensions are in millimeters.
　　　　　B.　This drawing is subject to change without notice.
　　　　　C.　Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

TEXAS INSTRUMENTS
www.ti.com

PS (R-PDSO-G8)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

6x1,27

8x0,55

6x1,27

8x1,75

7,40

7,40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

Example
Non-Solder Mask Opening
(See Note E)

0,60

1,80

0,07
All Around

4212188/A   09/11

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Publication IPC-7351 is recommended for alternate designs.
         D.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
              contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
         E.   Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

P (R−PDIP−T8)   PLASTIC DUAL−IN−LINE PACKAGE

$\dfrac{0.400\ (10,16)}{0.355\ (9,02)}$

8   5

$\dfrac{0.260\ (6,60)}{0.240\ (6,10)}$

1   4

$\dfrac{0.070\ (1,78)}{0.045\ (1,14)}$

$\dfrac{0.045\ (1,14)}{0.030\ (0,76)}$

0.020 (0,51) MIN

0.200 (5,08) MAX

$\dfrac{0.325\ (8,26)}{0.300\ (7,62)}$

0.015 (0,38)

Gauge Plane

Seating Plane

0.125 (3,18) MIN

0.010 (0,25) NOM

0.100 (2,54)

$\dfrac{0.021\ (0,53)}{0.015\ (0,38)}$

0.430 (10,92)
MAX

⊕ | 0.010 (0,25) Ⓜ

4040082/E   04/2010

NOTES: A.   All linear dimensions are in inches (millimeters).
            B.   This drawing is subject to change without notice.
            C.   Falls within JEDEC MS−001 variation BA.

IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (http://www.ti.com/sc/docs/stdterms.htm) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.